

85V N-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

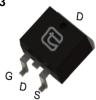
Product Summary

 V_{DS} 85V I_{D} (at V_{GS} = 10V) 85A $R_{DS(ON)}$ (at V_{GS} = 10V) < 8.8m Ω

100% UIS Tested

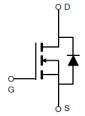


TO-263









Part Number Package Type		Form	Marking
TTB85N08AA	TO-263	Tape&Reel	TTB85N08AA
TTP85N08AA	TO-220	Tube	TTP85N08AA

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	85	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current B	T _C =25°C	I _D	85	۸
Continuous Drain Current B	T _C =100°C		62	Α
Pulsed Drain Current ^A		I _{DM}	340	Α
Avalanche Current A		I _{AS}	44	А
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	290	mJ
Power Dissipation ^C	T _C =25°C	P _D	157	W
	T _C =100°C		78	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 175	°C
Thermal Characteristics				

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	0.95	00.00	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W	



Commeltor - I	Baramatar.	Conditions		Value			He!to
Symbol	Parameter			Min	Тур	Max	Units
STATIC F	PARAMETERS				-		
BV_{DSS}	Drain-Source Breakdown Voltage	I _D =250μA,V _{GS} =0V		85			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =85V, V _{GS} =0V	T _J =25°C T _J =125°C			1 100	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$				±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA		2	3	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =30A			8	8.8	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A			30		S
V _{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V				1	V
I _s	Maximum Body-Diode Continuous Current B					85	Α
DYNAMIC	PARAMETERS					•	
C _{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 40V, f = 1MH_Z$			5585		
C _{oss}	Output Capacitance				248		pF
C _{rss}	Reverse Transfer Capacitance				219		
R_g	Gate Resistance	f =1MH _Z			1.6		Ω
SWITCHI	NG PARAMETERS				-		
Q_g	Total Gate Charge	V _{GS} =10V,V _{DS} =40V, I _D =20A			92		
Q_{gs}	Gate Source Charge				27		nC
Q_{gd}	Gate Drain Charge				21		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 40V, I_{D} = 20A,$ $R_{G} = 2.5\Omega$			24		
t _r	Turn-On Rise Time				19		ns
$T_{D(off)}$	Turn-Off Delay Time				70		
t _f	Turn-Off Fall Time				30		
t _{rr}	Body Diode Reverse Recovery Time				37		ns
Q _{rr}	Body Diode Reverse Recovery Charge				58		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

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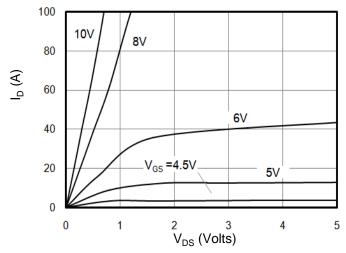
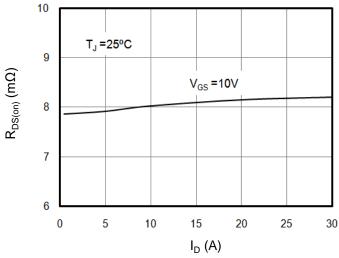


Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics



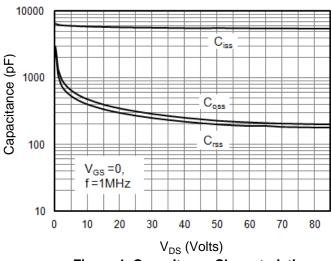
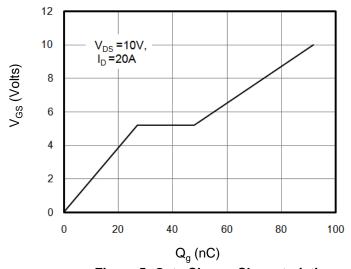


Figure 3: On-Resistance vs. Drain Current

Figure 4: Capacitance Characteristics



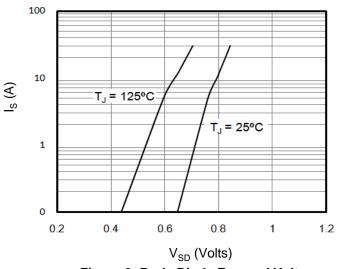


Figure 5: Gate Charge Characteristics

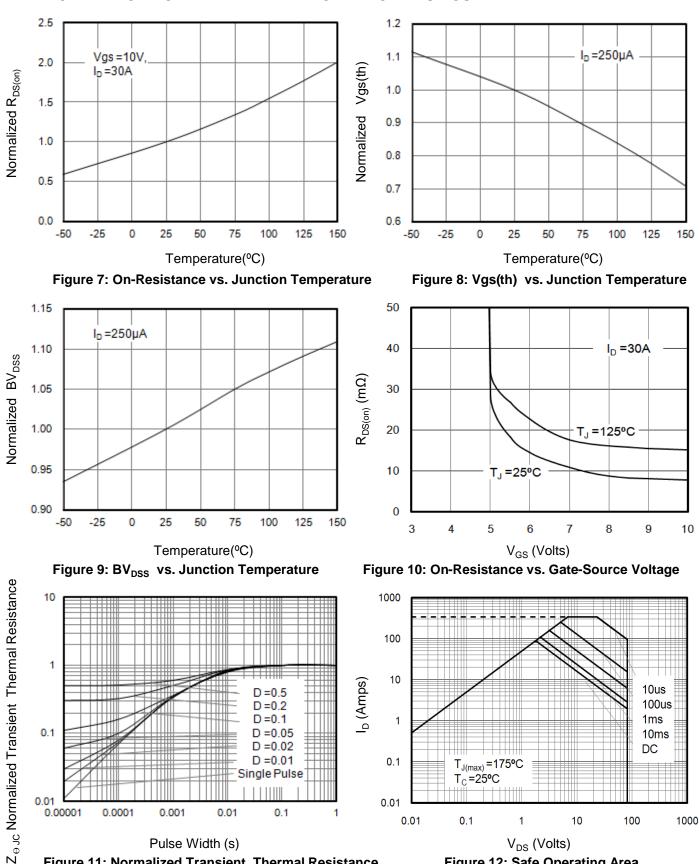
Figure 6: Body Diode Forward Voltage



V_{DS} (Volts)

Figure 12: Safe Operating Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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Pulse Width (s)

Figure 11: Normalized Transient Thermal Resistance



Figure A: Gate Charge Test Circuit and Waveforms

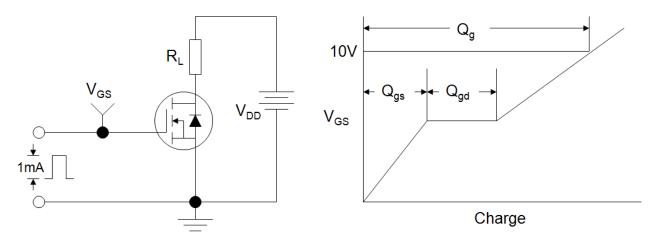


Figure B: Resistive Switching Test Circuit and Waveforms

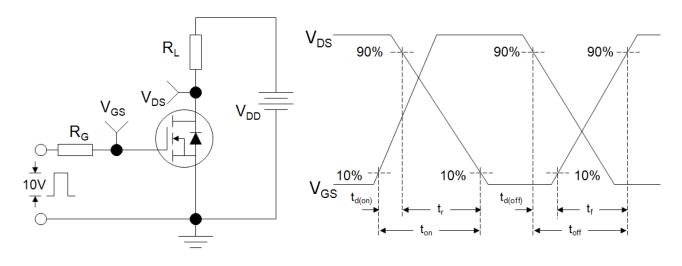
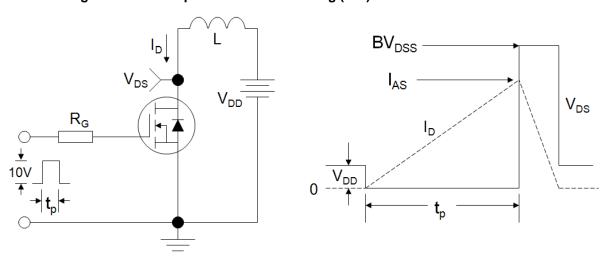


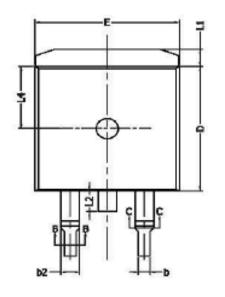
Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms

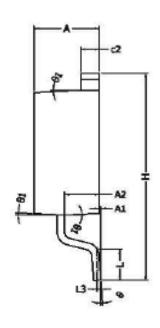


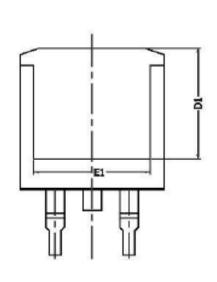
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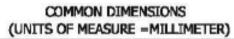


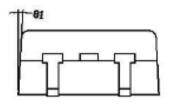
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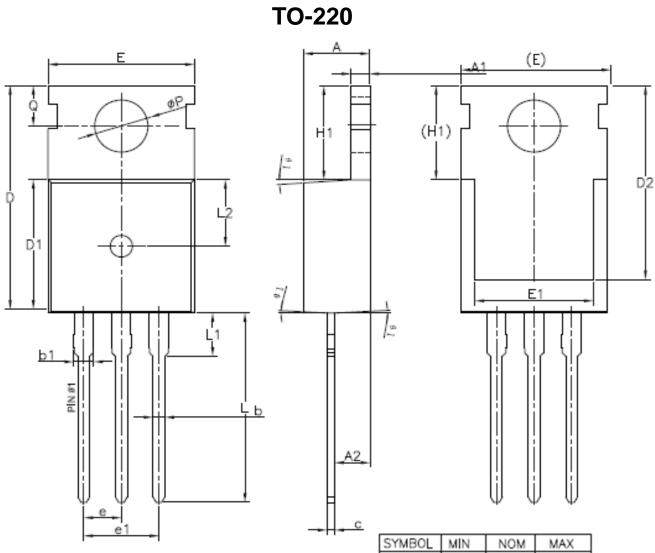


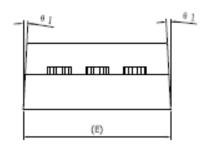




SYMBOL	MIN	NOM	MAX	
A	4.40	4.50	4.60	
A1	0	0.10	0.25	
A2	2.20	2.40	2.60	
b	0.76		0.89	
b1	0.75	0.80	0.85	
b2	1.23		1.37	
b3	1.22	1.27	1.32	
C	0.47		0.60	
c1	0.46	0.51	0.56	
c2	1.25	1.30	1.35	
D.	9.10	9.20	9.30	
D1	8.00			
E	9.80	9.90	10.00	
E1	7.80			
е	2.54 BSC			
Н	14.90	15.30	15.70	
L	2.00	2.30	2.60	
L1	1.17	1.27	1.40	
12			1.75	
L3	0.25BSC			
L4	4.60 REF			
0	0°		8°	
θ1	1°	3°	5°	







SYMBOL	MIN	NOM	MAX
Α	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	_	0.90
b1	1.27	1	1.40
С	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	_	13.70
Ε	9.70	9.90	10.20
E1	7.80	8.00	8.20
е	2	2.54BSC	
e1	5.08BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	_	_	3.50
L2	4.60REF		
øΡ	3.55	3.60	3.65
Q	2.73	_	2.87
01	1*	3*	5*



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